# **IGBT**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on–state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co–packaged free wheeling diode with a low forward voltage.

#### **Features**

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

## **Typical Applications**

- Inductive Heating
- Consumer Appliances
- Soft Switching

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	40 20	A
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	200	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l <sub>F</sub>	40 20	A
Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>FM</sub>	200	Α
Gate-emitter voltage	$V_{GE}$	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	192 77	W
Operating junction temperature range	TJ	–55 to +150	ç
Storage temperature range	T <sub>stg</sub>	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

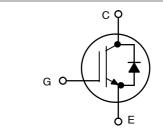
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

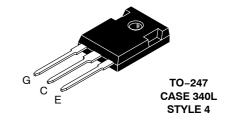


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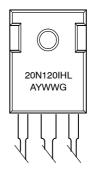
http://onsemi.com

20 A, 1200 V V<sub>CEsat</sub> = 1.80 V E<sub>off</sub> = 0.7 mJ





## **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTB20N120IHLWG	TO-247 (Pb-Free)	30 Units / Rail

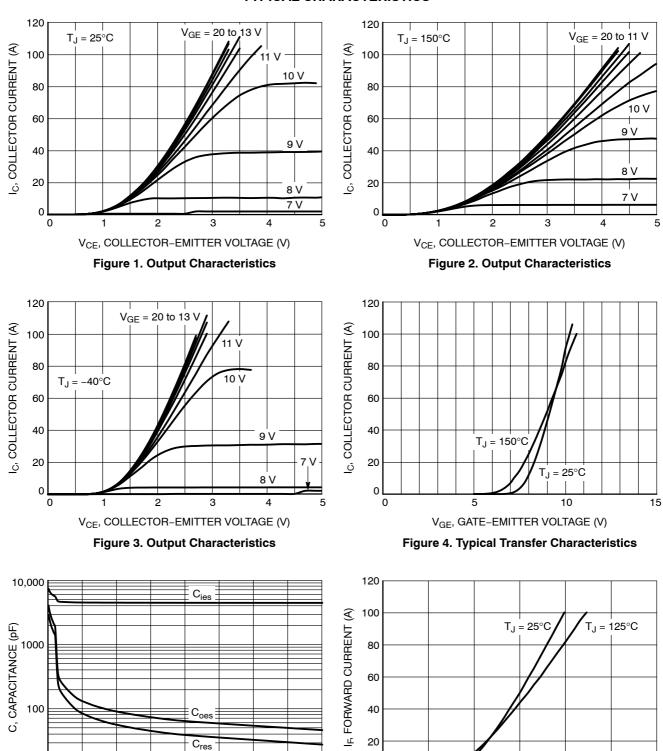
# THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.65	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ hetaJC}$	2.0	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•	•		•		L
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V}, I_{C} = 500 \mu\text{A}$	V <sub>(BR)CES</sub>	1200	_	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 20 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 20 A, T <sub>J</sub> = 150°C	V <sub>CEsat</sub>	-	1.80 2.0	2.2 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	V <sub>GE(th)</sub>	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	$V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}$ $V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}, T_{J=} 150^{\circ}\text{C}$	I <sub>CES</sub>	- -	_ _	0.5 2.0	mA
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	100	nA
DYNAMIC CHARACTERISTIC	•			•		
Input capacitance		C <sub>ies</sub>	-	4700	-	pF
Output capacitance	$V_{CE}$ = 20 V, $V_{GE}$ = 0 V, f = 1 MHz	C <sub>oes</sub>	-	155	-	
Reverse transfer capacitance	1	C <sub>res</sub>	-	100	-	
Gate charge total		$Q_g$		200		nC
Gate to emitter charge	V <sub>CE</sub> = 600 V, I <sub>C</sub> = 20 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>		36		
Gate to collector charge	]	Q <sub>gc</sub>		98		
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>		235		ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 20 \text{ A}$ $R_{q} = 10 \Omega$	t <sub>f</sub>		180		
Turn-off switching loss	V <sub>GE</sub> = 0 V/ 15V	E <sub>off</sub>		0.7		mJ
Turn-off delay time	T <sub>J</sub> = 125°C	t <sub>d(off)</sub>		235		ns
Fall time	$V_{CC} = 600 \text{ V, } I_{C} = 20 \text{ A}$ $R_{q} = 10 \Omega$	t <sub>f</sub>		250		1
Turn-off switching loss	V <sub>GE</sub> = 0 V/ 15V	E <sub>off</sub>		1.60		mJ
DIODE CHARACTERISTIC						
Forward voltage	V <sub>GE</sub> = 0 V, I <sub>F</sub> = 20 A V <sub>GE</sub> = 0 V, I <sub>F</sub> = 20 A, T <sub>J</sub> = 150°C	V <sub>F</sub>		1.55 1.65	1.75	V

#### TYPICAL CHARACTERISTICS



V<sub>CE</sub>, COLLECTOR-EMITTER VOLTAGE (V) Figure 5. Typical Capacitance

100

125

150

75

10

 $\label{eq:VF} V_F, \, \text{FORWARD VOLTAGE (V)}$  Figure 6. Diode Forward Characteristics

1.5

2.0

2.5

3.0

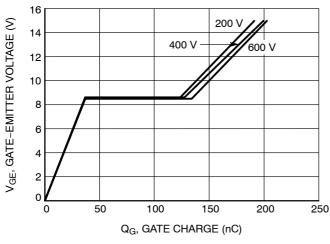
0.5

1.0

0

200

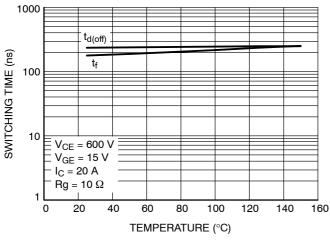
#### **TYPICAL CHARACTERISTICS**



(E)  $V_{CE}$  = 600 V1.6 TURN-OFF SWITCHING LOSS  $V_{GE} = 15 V$  $I_{\rm C} = 20 {\rm A}$ 1.4  $Rg = 10 \Omega$ 1.2 1.0 0.8 0.6 0.4 0.2 . Д 0 20 100 120 TEMPERATURE (°C)

Figure 7. Typical Gate Charge

Figure 8. Energy Loss vs. Temperature



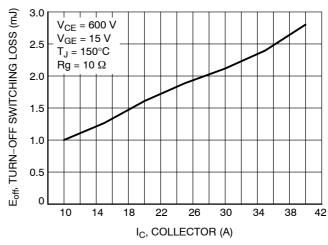
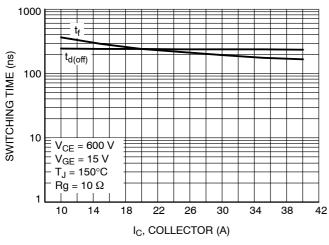


Figure 9. Switching Time vs. Temperature

Figure 10. Energy Loss vs. I<sub>C</sub>



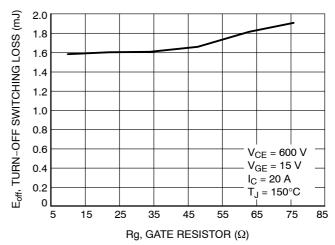


Figure 11. Switching Time vs. I<sub>C</sub>

Figure 12. Energy Loss vs. Rg

#### TYPICAL CHARACTERISTICS

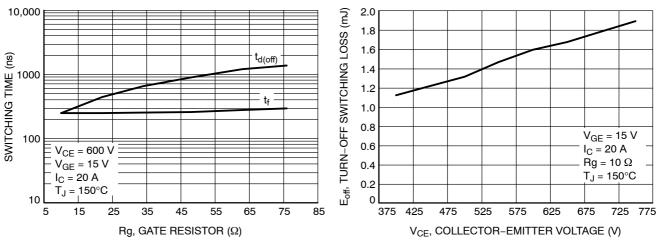


Figure 13. Switching Time vs. Rg

Figure 14. Energy Loss vs. V<sub>CE</sub>

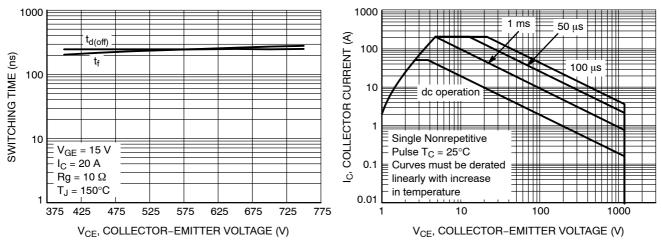


Figure 15. Switching Time vs. V<sub>CE</sub>

Figure 16. Safe Operating Area

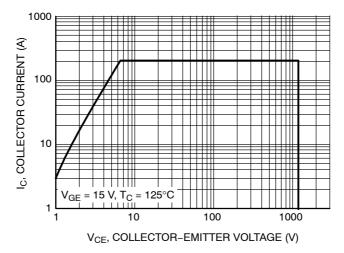


Figure 17. Reverse Bias Safe Operating Area

#### TYPICAL CHARACTERISTICS

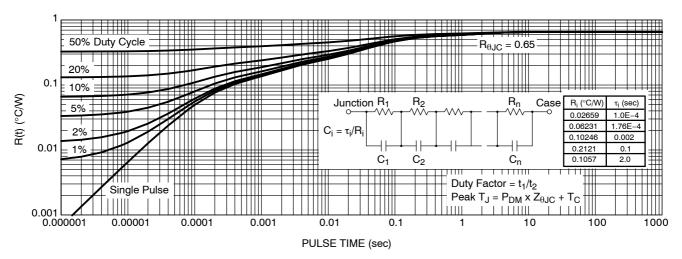


Figure 18. IGBT Transient Thermal Impedance

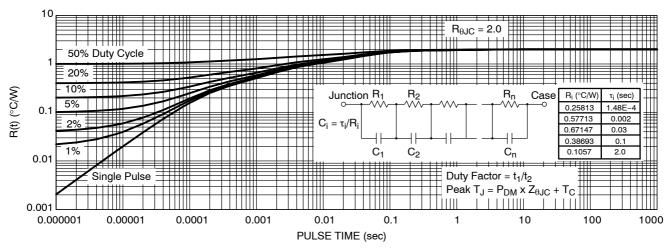


Figure 19. Diode Transient Thermal Impedance

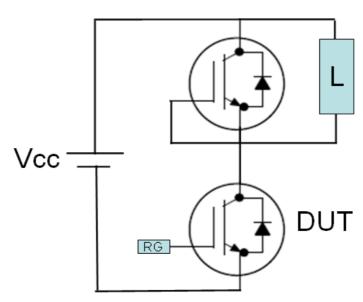


Figure 20. Test Circuit for Switching Characteristics

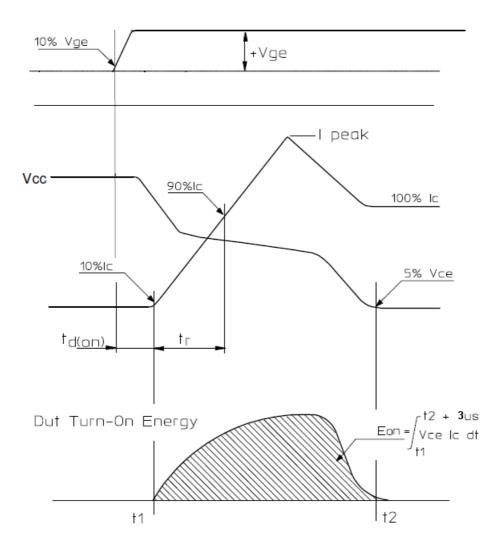


Figure 21. Definition of Turn On Waveform

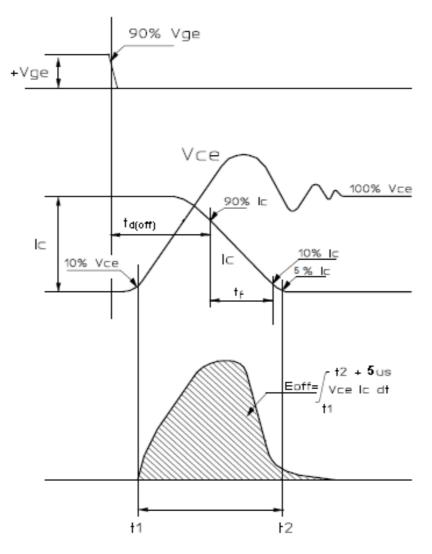
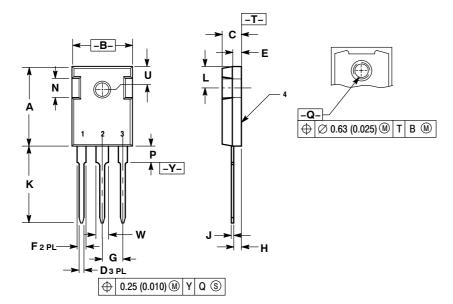


Figure 22. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

TO-247 CASE 340L-02 **ISSUE F** 



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Е	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45	5.45 BSC		BSC
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
P		4.50		0.177
ø	3.55	3.65	0.140	0.144
U	6.15	BSC	0.242 BSC	
W	2.87	3.12	0.113	0.123

STYLE 4: PIN 1. GATE

- 2. COLLECTOR 3. EMITTER
- 4 COLLECTOR

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